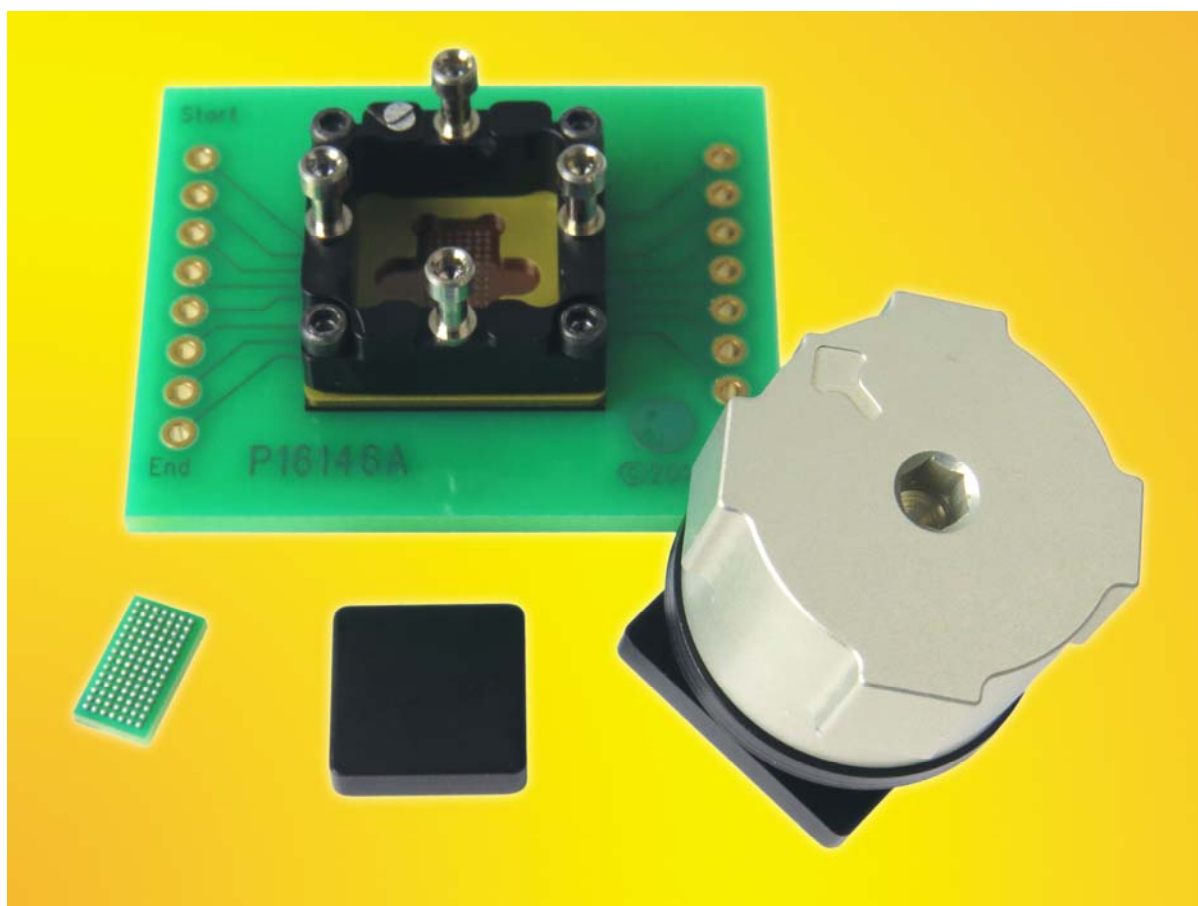




30 GHz Bandwidth Socket for IDT's FCCSP 98

Socket your 98 pin BGA packages on any PCB without significant performance loss and without soldering

EAGAN, MN - September, 2016 - Ironwood Electronics has recently introduced a new high performance BGA socket for 0.5mm pitch BGA 98 pin IC's. The SG-BGA-7295 socket is designed for IDT's flip chip chip scale package (FCCSP) and operates at bandwidths up to 30 GHz with less than 1dB of insertion loss. The sockets are designed to dissipate up to several watts without extra heat sinking and can handle up to 100 watts with custom heat sink. The contact resistance is typically 20 milliohms per pin. The socket connects all pins with 30 GHz bandwidth on all connections. The socket is mounted using supplied hardware on the target PCB with no soldering, and uses smallest footprint in the industry. The smallest footprint allows inductors, resistors and decoupling capacitors to be placed very close to the device for impedance tuning. The socket also incorporates a simple hardware installation method so that IC's can be changed out quickly.



The SG-BGA-7292 sockets are constructed with high performance and low inductance elastomer contactor. The temperature range is -35°C to +100°C. The pin self inductance is 0.15 nH and mutual inductance of 0.025 nH. Capacitance to ground is 0.01 pF. Current capacity is 2 amps per pin. Elastomer requires proper force for operation which is applied through a torque indicating compression screw. Typical IC's that can be tested using this skt have 98 balls, 4x7.5mm with 0.5mm pitch and 7x14 ball array.

(September, 2016)